### T-1 3/4 (5mm) BI-COLOR RIGHT ANGLE LED INDICATOR

Part Number: WP59BL/EGW

High Efficiency Red Green

#### Features

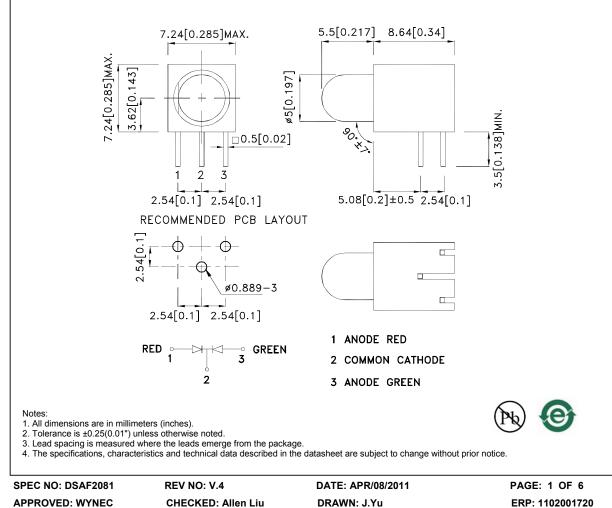
- Pre-trimmed leads for pc board mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

#### Package Dimensions



	Selection Guide					
_	Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
				Min.	Тур.	201/2
	WP59BL/EGW	High Efficiency Red (GaAsP/GaP)	White Diffused	50	100	60°
		Green (GaP)	White Diffused	20	60	

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Green	625 568		nm	l⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	l⊧=20mA
С	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	I⊧=20mA
lr	Reverse Current	High Efficiency Red Green		10 10	uA	VR = 5V

#### Electrical / Optical Characteristics at TA=25°C

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

#### Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Green	Units	
Power dissipation	75	62.5	mW	
DC Forward Current	30	25	mA	
Peak Forward Current [1]	160	140	mA	
Reverse Voltage	5	V		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

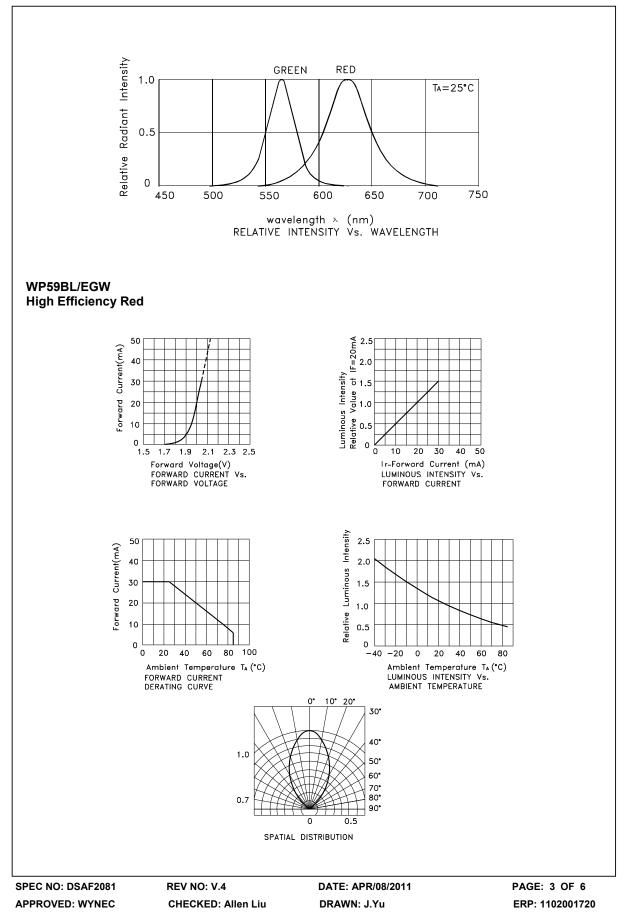
Notes:

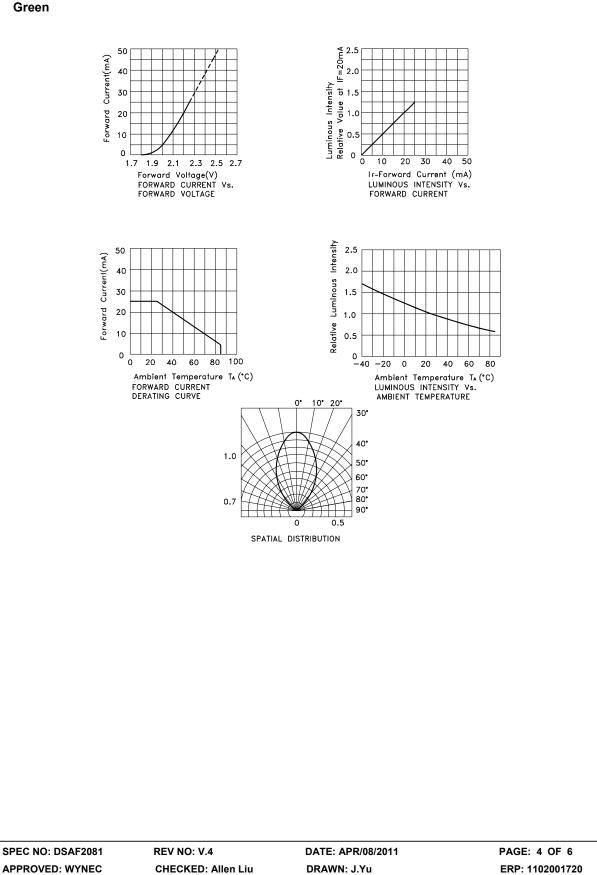
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

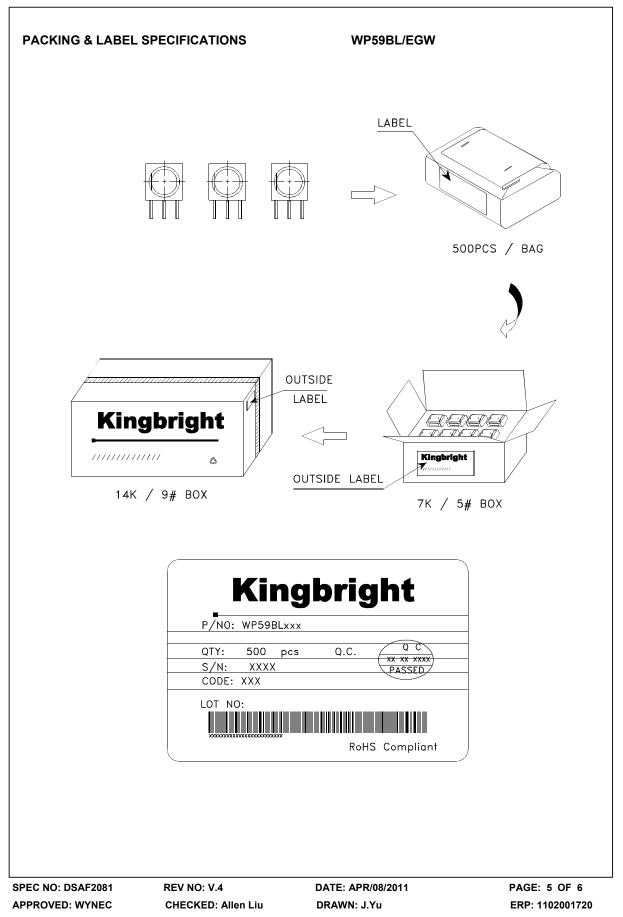
2. 2mm below package base.
3. 5mm below package base.

SPEC NO: DSAF2081 APPROVED: WYNEC

REV NO: V.4 CHECKED: Allen Liu DATE: APR/08/2011 DRAWN: J.Yu

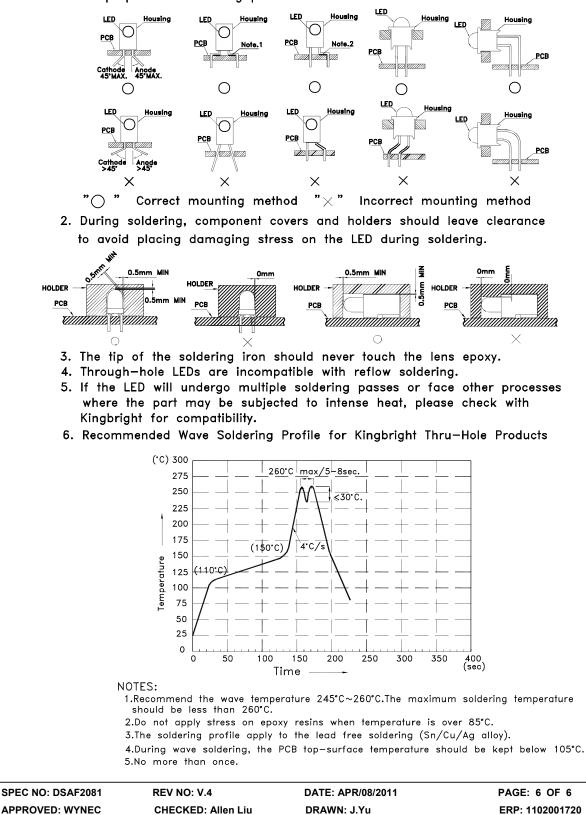






#### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DRAWN: J.Yu

ERP: 1102001720

**CHECKED: Allen Liu**